

SEMICONDUCTOR PACKAGE

ABSTRACT

Disclosed in the embodiments of the disclosure is a semiconductor package. The semiconductor package includes a first base plate, a first semiconductor structure, a second base plate and a filling layer. The first base plate has a first surface. The first surface includes a first signal transmission region and a second signal transmission region. The first semiconductor structure is located on the first surface of the first base plate and electrically connected to the first signal transmission region. The second base plate is located on the first base plate and includes a base and a first interconnection surface located on the base. The first interconnection surface of the second base plate is away from the first surface of the first base plate. The first interconnection surface has a first interconnection region and a second interconnection region that communicate with each other. The first interconnection region is electrically connected to the second signal transmission region. The filling layer seals the first semiconductor structure, the second base plate and the first surface of the first base plate. The first interconnection region is not sealed by the filling layer, and the second interconnection region is sealed by the filling layer. There is a preset height between a top surface of the filling layer on the second interconnection region and the first interconnection region.

[Fig. 1]